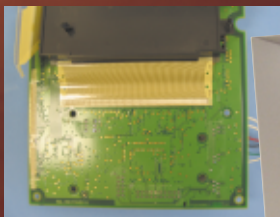
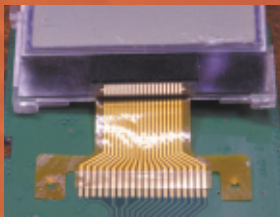
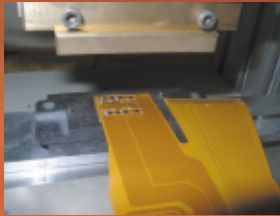


## Typical Applications



# Precise, consistent heat bonding & manual methods of affixing flex circuits

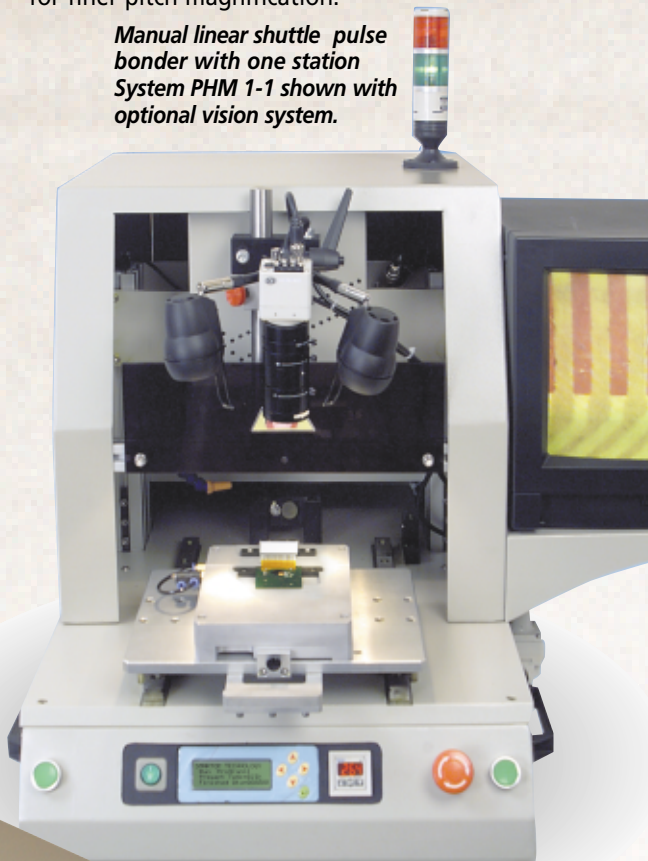
## THE PHM SERIES PULSED HEAT BONDING SYSTEMS

- Easily programmable profiles for total flexibility, including idle, preheat and reflow temperatures
- Unique pulse head floating thermode and digital pressure control for uniform temperature distribution, fast heating and cool-down
- Microprocessor-based controller for exact temperature control.

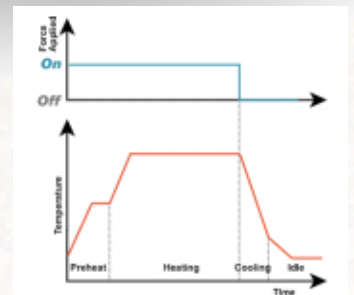
Fancort's PHM pulsed heat bonders, also known as hot bar soldering systems, will bond flex circuits to printed wiring boards or to ceramic substrates. These bench-top machines also solder intricate surface-mounted edge connectors and ribbon cables to circuit boards. Unlike the fixed temperature heat seal system (shown on opposite page), the PHM provides unlimited flexibility with easily programmable heat profiles to attain exact ramp-up, control, solder and cool-down temperatures. All controls are front-mounted for ease of access. System components include a floating titanium thermode to control temperatures and pressure throughout the production sequence, plus a custom holding fixture, available through Fancort, to retain circuit board or substrate during repeated bonding sequences. A sliding linear shuttle is also

included with System PHM 1-1. The upgraded System PHM 2-2, provides a rotary, 2-station shuttle — speeding production by permitting the loading of a second fixture while processing takes place on the first. An optional B&W or color camera system with monitor is available for finer pitch magnification.

*Manual linear shuttle pulse bonder with one station System PHM 1-1 shown with optional vision system.*



*System PHM 2-2 pneumatic rotary pulse bonder with two-station shuttle. Vision is also available.*



*For added flexibility, PHM systems offer profiling capability.*